

5. First Policy
General
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November 26th, 1959

COCOM Document No. 3715.66/1B

COORDINATING COMMITTEE

RECORD OF DISCUSSION

ON

ITEM 1566 - EQUIPMENT ... TO PRODUCE ELECTRONIC ASSEMBLIES

5th and 17th November, 1959

Present: Belgium (Luxembourg), Canada, France, Germany, Italy, Japan, Netherlands, United Kingdom, United States.

References: COCOM 3700.1, 3715.00/1 and W.P.1566/1.

1. The UNITED STATES Delegation proposed the addition of a new part (c) reading as follows:

"by automatically or semi-automatically assembling, wiring and/or packaging mounted modular insulated panels (including wafers) referred to in (a) and (b) above."

2. The new definition of Item 1566 would thus read as follows:

"Equipment specially designed to produce electronic assemblies:

- (a) by depositing or printing on insulating panels (including plates and wafers), or otherwise forming in situ, component parts other than basic wiring; or
- (b) by automatically inserting and/or soldering components on insulating panels (including plates and wafers), to which wiring is applied by printing or other means;
- (c) by automatically or semi-automatically assembling, wiring and/or packaging mounted modular insulated panels (including wafers) referred to in (a) and (b) above."

3. All Delegations accepted the new definition ad referendum. The UNITED KINGDOM Delegation, however, expressed reserves as to the heading of this item, which in their view would be likely before long to cover civilian-type material.

CONCLUSION: The COMMITTEE agreed to resume study of this item during the second round of discussion only if the ad referendum agreement were not confirmed in the meantime.

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